

	ATTY. DOCKET NO.:	APPLICATION NO.:
	81421-4038	
	APPLICANT:	
	Steen Ørsted ANDERSEN	
	FILING DATE:	GROUP:
	March 9, 2004	

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
SDI	AA	6,240,933 B1	6/2001	Bergman	134	1.3	
	AB	6,312,797	11/2001	Yokokawa et al.	428	336	
	AC	2002/0062841	5/2002	Twu et al.	134	3	
	AD						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AE							
	AF							
	AG							
	AH							
	AI							

## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

SDI	AJ	Seiji Fujino et al., "Silicon Wafer Direct Bonding through the Amorphous Layer", Jp.n.. J. Appl. Phys., Vol. 34, pp. 1322-1324 (1995)
	AK	
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	AM	
	AN	
	AO	

EXAMINER	DATE CONSIDERED
<i>Steen Ørsted Andersen</i>	6/7/05
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	



ATTY. DOCKET NO.:

4717-10500

APPLICATION NO.:

10/808,288

APPLICANT:

C. Maleville et al.

FILING DATE:

March 25, 2004

GROUP:

2812

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EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
SDI	AA	2002/0020436 A1	2/2002	Bergman	134	30	
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## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
SDI	AE	EP 0971 396 A1	1/2000	Europe			X	
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	AG							
	AH							
	AI							

## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

	AJ	)
	AK	
	AL	
	AM	
	AN	
	AO	

EXAMINER

*Stanette Dase*

DATE CONSIDERED

*6/7/05*

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.